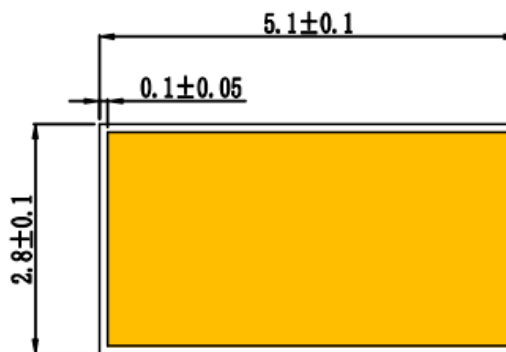
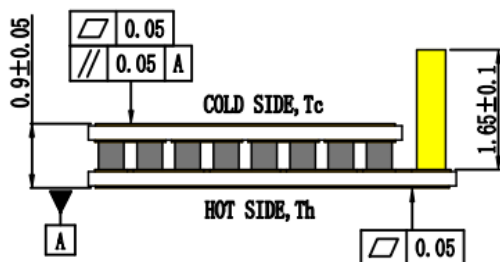
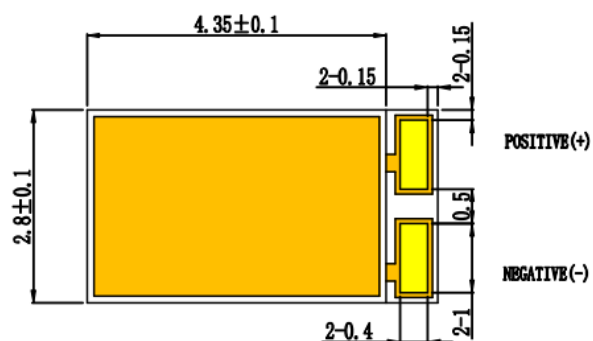
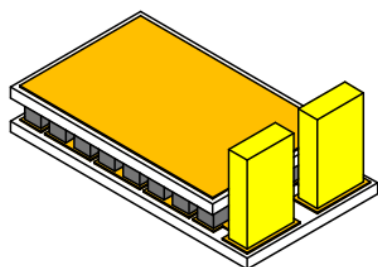


Product Code: TEM1-02016P

1. 组件尺寸(mm) Module Dimensions



2. 电参数 Electrical Parameters

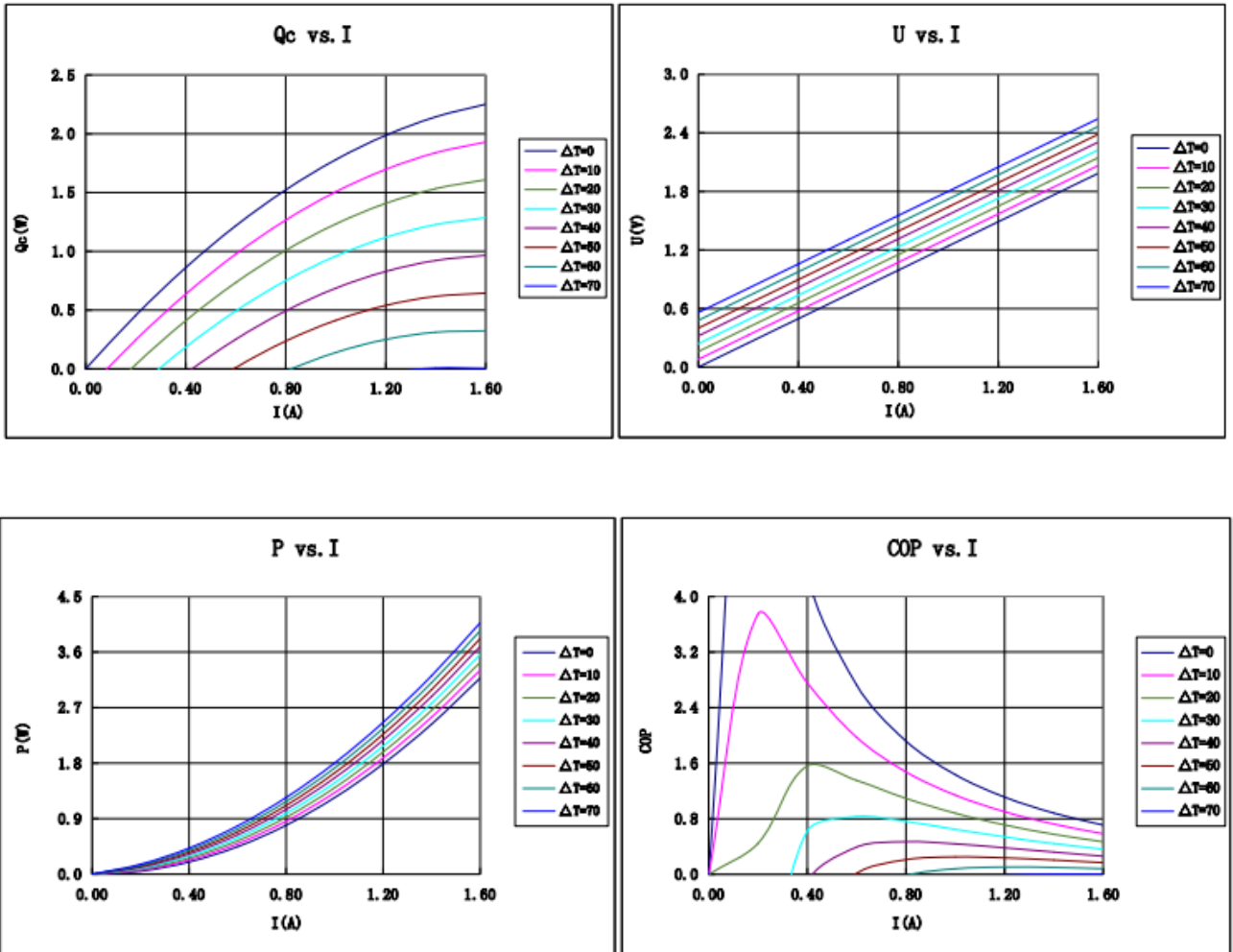
性能参数								
Th=27℃				Th=85℃				Ta=27℃
$\Delta T_{max}/℃$	Qc max/W	Umax/V	I _{max} /A	$\Delta T_{max}/℃$	Qc max/W	Umax/V	I _{max} /A	ACR/Ω
70.3	2.25	2.4	1.6	93.4	2.93	2.86	1.6	1.24±10%

3. 标注信息 Graphic Notes

- 半导体材料：碲化铋 Bi_2Te_3 alloy , 20 P, N Couples
- Thermoelectric material: Bismuth Telluride, 20 P, N Couples
- 陶瓷基板：AlN 白色
Ceramic plate: AlN white color
- 金属化层组成：Cu/Ni/Pd/Au, 厚度: $\geq 20\mu\text{m}/3-6\mu\text{m}/0.075\mu\text{m}/0.1-0.15\mu\text{m}$
- Metallic layers: Cu/Ni/Pd/Au, Thickness: $\geq 20\mu\text{m}/3-6\mu\text{m}/0.075\mu\text{m}/0.1-0.15\mu\text{m}$
- 内部焊料组成：AuSn; 最高允许工艺温度 265 摄氏度, 2 分钟
Interior solder composition: AuSn, Max. process temperature 265 Celsius Degree for 2 min.

4. Performance curve

Th = 27C



SPECIFICATIONS

Th = 85C

